PRODUCT SPECIFICATION

CS2004C-D-YSXFDYN-104

V1.0

February 27, 2009

E Easterntronic LCD Group

REVISION RECORD

REV	Description	Date
V1.0	First Release	Feb 27, 2009

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1. Type Number And Description

Type Number : CS2004C-D-YSXFDYN-104

Description 20Characters X 4Lines

LCD Panel Yellow-green STN, Transflective

Viewing angle 6H

Duty 1/16

Bias 1/5

Operating Temperature: $-20^{\circ}C - 70^{\circ}C$

Storage Temperature : $-30^{\circ}C - 80^{\circ}C$

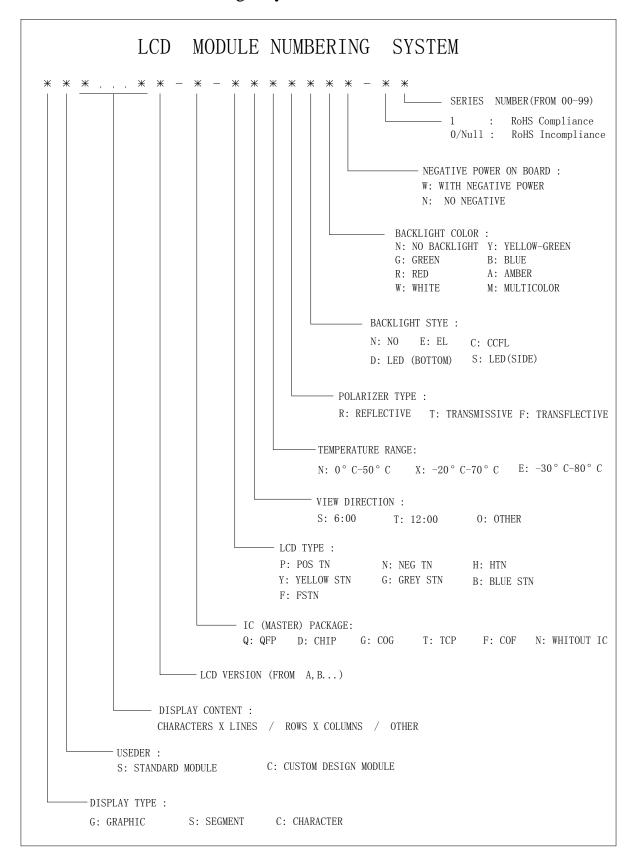
ST7066U-OA Or Equivalent Controller

IC package Bonding

BackLight Yellow-green LED, Bottom

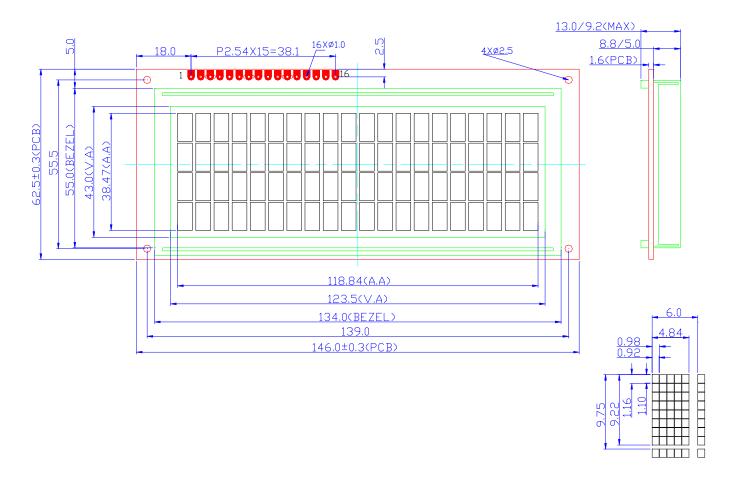
Limit Resistor of B/L RB1=0 ohm

2.LCD Module Numbering System



3.Mechanical Specifications

ITEM	STANDARD VALUE	UNIT
NUMBER OF CHARACTERS	20 CHARACTERS X 4LINES	
CHARACTER FORMAT	5 X 8 DOTS	
MODULE DIMENSION	146.0(W) X 62.5(H) X 13.0(T)	mm
EFFECTTVE DISPLAY AREA	123.5(W) X 43.0(H)	mm
CHARACTER SIZE	4.84(W) X 9.22(H)	mm
CHARACTER PITCH	6.0(W) X 9.75(H)	mm
DOT SIZE	0.92(W) X 1.1(H)	mm
DOT PITCH	0.98(W) X 1.16(H)	mm
APPROX WEIGHT	TBD	g
LCD TYPE	Yellow-green STN, TRANSFLECT	ΓΙVΕ
DUTY AND BIAS	1/16 DUTY; 1/5 BIAS	
VIEWING DIRECTION	6:00	
BACK LIGHT	Yellow-green LED, BOTTEM	



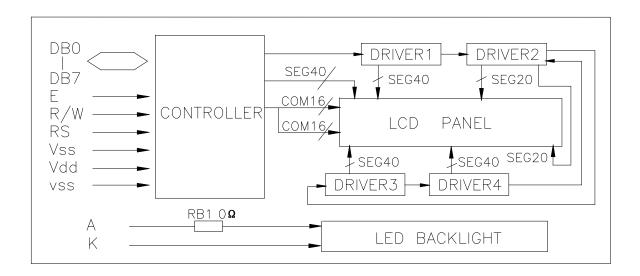
^{*} Remark : Non-specific tolerance refers this model. (± 0.2 mm)

4. Electrical Block Diagram

Pin Definition 4.1

PIN	SYMBOL	FUNCTION
1	Vss	Power Supply(0V,GND)
2	Vdd	Power Supply For Logic
3	Vo	Contrast Adjust
4	RS	Instruction/Data Register Select
5	R/W	Data Read/Write
6	Е	Enable Signal
7-14	DB0-DB7	Data Bus Line
15	A	Power Supply For LED B/L(+4.2V)
16	K	Power Supply For LED B/L(0V)

Electrical Block Diagram 4.2



Display Character Address Code 4.3

DISPLAY POSITION	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
DDRAM	00	01	02	03	04	05	06	07	08	09	OΑ	0B	0C	OD	0E	0F	10	11	12	13
2210 1111	40	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F	50	51	52	53
ADDRESS	14	15	16	17	18	19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	25	26	27
	54	55	56	57	58	59	5A	5B	5C	5D	5E	5F	60	61	62	63	64	65	66	67

5. Absolute Maximum Ratings

Electrical Maximum Ratings(Ta=25deg C) 5.1

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Supply Voltage (Logic)	Vdd – Vss	-	0	7.0	V
Supply Voltage (LCD Drive)	Vdd – V0	-	0	11.5	V
Input Voltage	Vi	-	-0.3	Vdd +0.3	V

5.2 **Environmental Conditions**

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Operating Temp	Topr	Dry	-20	70	deg C
Storage Temp	Ttsg	Dry	-30	80	deg C

6.ELECTRICAL SPECIFICATIONS

Electrical Characteristics at Ta=25 deg C, Vdd = 5V + / - 5%6.1

ITEM	SYMBOL	CONDITION	MIN	TYP	MAX	UNIT
Supply Voltage (logic)	Vdd-Vss	-	4.5	5	5.5	V
Supply Voltage (LCD)	Vdd-V0	Vdd = 5V	4.5	4.7	5.0	V
Input signal voltage	V-ih	"H" level	0.7Vdd	-	Vdd	V
(for E, DB0-7,R/W,RS)	V-il	"L" level	0	-	0.6	V
Supply Current (logic)	Icc	-	0.9	1	1.2	mA
Supply Current (LCD)	lo	-	0.15	0.22	0.27	mA
Supply Voltage (B/L)	V-bl	see note 1	3.9	4.2	4.4	V
*Supply Current (B/L)	lf	see note 1	-	200	540	mA
*Peak forward current(B/L)	Ifp	I mseo pulse 10% Duty Cycle	-	-	1944	mA
*Power dissipation(B/L)	Pd	1070 Daty Oydic	-	-	2376	mW

Note 1: LED backlight chips are arranged in two branches of 2 in series

*For operation above 25°C, the If \ Ifp&Pd must be derated, the current derating is -10.8 mA/ $^{\circ}$ C for DC drive and -11.13 mA/ $^{\circ}$ C for pulse drive, the power dissipation is -45.36 mW / $^{\circ}$ C. The Blacklight working current must not more than 60% of the Ifmax or Ifpmax according to the working temperature.

6.2 Timing Specifications at Ta = 25 deg C, Vdd = 5V + /-10%, Vss = 0V

6.2.1 Write mode

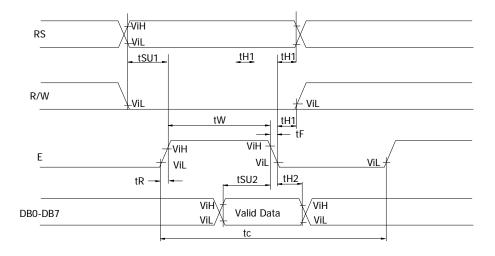
ITEM	SYMBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsul	0	-	ns
R/W and RS hold time	tH1	10	Ī	ns
Data set-up time	tsu2	40	-	ns
Data hold time	tH2	10	-	ns

6.2.2 Read mode

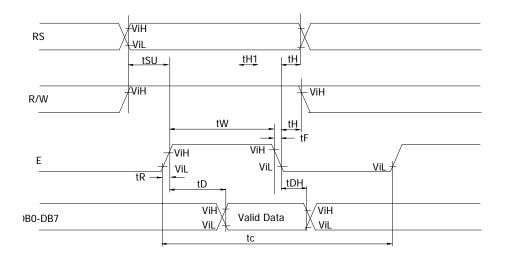
ITEM	SYBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsu	0	-	ns
R/W and RS hold time	tH	10	-	ns
Data output delay	tD	-	120	ns
Data hold time	tDH	20	-	ns

6.2.3 Timing Diagram

WRITE MODE TIMING DIAGRAM

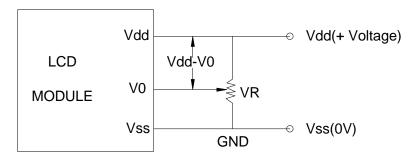


READ MODE TIMING DIAGRAM



7. EXAMPLE OF POWER SUPPLY

It is recommended to apply a potentiometer for the contrast adjust due to the tolerance of driving voltage and its temperature dependence.



Vdd - V0: LCD Driving Voltage

VR: 10K - 20K

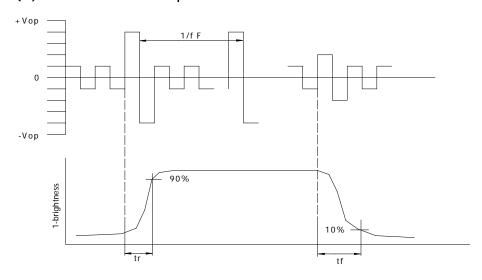
8. Electro-Optical Characteristic

ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT	REF.	
Contrast	CR	25℃		12	1		Note1	
Rise Time	tr	25℃		160	240	ms	Note2	
Fall Time	tf	25℃		100	150	ms	note 2	
Viewing Angle	θ 1- θ 2	25℃			60	DEG	Noto 2	
Viewing Angle	Ø1, Ø2	25 C	-40		40	DEG	Note 3	
Frame Frequency	Ff	25℃		70		Hz	note 2	

Note(1): Contrast ratio is defined under the following condition:

- brightness of non-selected condition brightness of selected condition
- Temperature-----25C (a).
- (b). Frame Frequency-----64Hz
- (c). Viewing angle----- $\theta = 0$, $\emptyset = 0$
- (d). Operating Voltage---4.7V

Note(2): definition of response time:

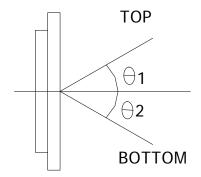


Condition:

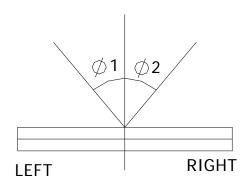
- (a). Temperature-----25C
- (b). Frame Frequency-----64Hz
- Viewing angle----- $\theta = 0$, $\emptyset = 0$ (c).
- Operating Voltage---4.7V (d).

Note(3): definition of view angle:

TOP-BOTTOM DIRECTION



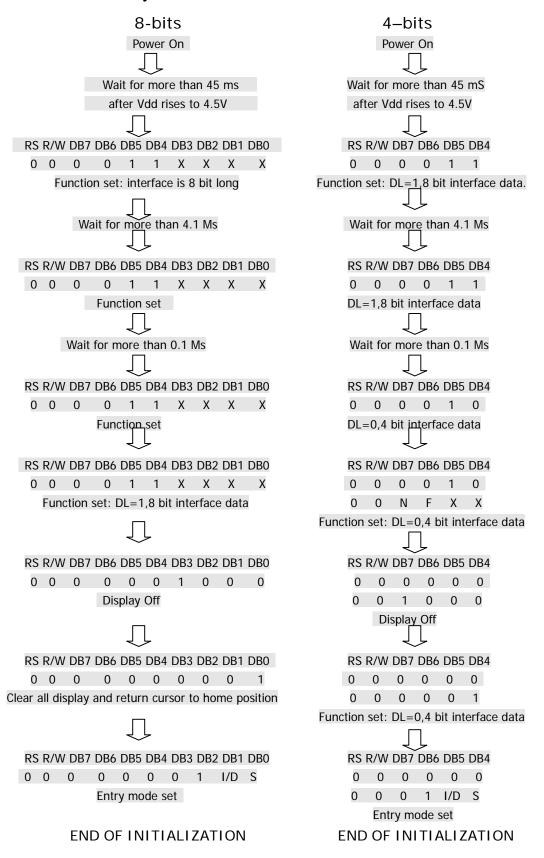
RIGHT-LEFT DIRECTION



9.Instruction Table

Function	R	R	D	D	D	D	D	D	D	D	Description	Execu
							В				•	Time*
							3					(Max)
Clear	0	0									Clears entire display and returns the cursor to	-
Display											home position (address 0)	
Return	0	0	0	0	0	0	0	0	1	Χ	Return the cursor to the home position. DD RAM	1.64mS
Home											contents remain unchanged. Set DD RAM address	
											to zero.	
Entry	0	0	0	0	0	0	0	1	1	S	Set cursor moving direction and enable the	40 μ S
mode									/		shift of the display. These operations are	
set									D		performed during data write/read of DD RAM/CG	
											RAM. 1/D=1: increment; 1/D=0: decrement; S=1:	
											whole display shift when data is written.	
Display	0	0	0	0	0	0	1	D	С	В	Set display (D),cursor(C) and blinking of cursor(B)	40 μ S
ON/OFF											ON/OFF. D=1:display ON; D=0: display OFF.	
control											C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON;	
											B=0, Blink OFF.	
Cursor or	0	0	0	0	0	1	S	R	Χ	Χ	Move the cursor and shift the display without	40 μ S
Display							/	/			changing DDRAM contents. S/C=1: Display Shift;	
shift							С	L			S/C=0:Cursor move. R/L=1:shift to right;	
											R/L=0:shift to left.	
Function	0	0	0	0	1	D	N	F	Χ	Χ	Set interface data length (DL), number of display	40 μ S
Set						L					lines (N) and character font (F).DL=1: 8 bits;	
											DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines. $F=1$:	
											5X11 dots; F=0: 5X7 dots.	
Set CG	0	0	0	1			A(CG	I		Set CG RAM address. CG RAM data is sent and	40 μ S
RAM add											received after this setting.	
Set DD	0	0	1			Α	D	D			Set DD RAM address. DD RAM data is sent and	40 μ S
RAM Add											received after this setting.	
Read BF	0	1	В			1	AC	,			Read BUSY FLAG (BF) and the contents of the	0 μ S
& Addr			F								address counter. $BF=1$: internal operation; $BF=0$:	
											can accept instruction.	
Write Data	1	0	١	Νŀ	RΙ.	TE	E [ÞΑ	T	4	Write data into DD RAM or CG RAM.	40
to RAM												μ S **
Read Data	1	0		RI	EΑ	D	D	Α	ГΑ		Read data from DD RAM or CG RAM.	40
from RAM												μ S **

10.Initialization By Instruction



11.Software Examples

8-BIT OPERATION 8 characters X 2 lines

Function	RS RW D7 D6 D5 D4 D3 D2 D1 D0	DISPLAY DESCRIPTION
Power on delay		Initialization. No display appears.
Function set	0 0 0 0 1 1 0 0 X X	Sets 8-bit operation, 2-line display and 5*7
		dots character font.
Display OFF	0 0 0 0 0 0 1 0 0 0	Turn off display.
Display ON	0 0 0 0 0 0 1 1 1 0	Turn on display and cursor.
Entry Mode set	0 0 0 0 0 0 0 1 1 0	Set mode to increment the address by one
		and to shift the cursor to the right, at the
		time of write to the DD/CG RAM. Display
		is not shifted.
Write data to	1 0 0 1 0 0 1 1 1 1	O Write "O". Cursor incremented by one and
CG/DD RAM		shift to right.
Write data to	1 0 0 1 0 1 0 0 1 0	OR Write "R". Cursor incremented by one and
CG/DD RAM		shift to right
Write data to		ORIENT Write "I" "E" "N" "T".
CG/DD RAM		
Set DDRAM	0 0 1 1 0 0 0 0 0 0	ORIENT Set RAM address so that the cursor is
address		positioned at the head of the Second line
Write data to		ORIENT Write "D" "S".
CG/DD RAM		<u>DS</u>
Cursor or display	0 0 0 0 0 1 0 0 X X	ORIENT Shift only the cursor position to the left.
shift		<u>DS</u>
Write data to		ORIENT Write "I" "S" "P" "L" "A" "Y"
CG/DD RAM		<u>DISPLAY</u>

4-bit operation (4-bits 1 line)

Function	RS	RW	D7	D6	D5	D4	Display	Description
power on delay								Initialization. No display appears.
Frnction set	0	0	0	0	1	0		Sets to 4-bit operation. In this case, operation is handled as 8-bits by initialization,a nd Only this instruction completes with one write.
Frnction set	0	0	0	0	-	0 X		Sets 4 -bit operation, 1-line display and 5*7 dot character font. (number of display lines and character fontscannot be changed hence after.)
Display ON/OFF Control		0	0 1	0	0			Turn on display and cursor.
Entry Mode Set	0	0	0	0	0			Turn on display and cursor.
Write data to CG/DD/ARM	1	-	0 1	1	0			Write "O". Curaor incrementer by one and shift to right.
						9	same as 8-bi	t operation

12.Quality units

12.1 Purpose

This standard for quality assurance should define the quality of LCD module products to customer by EASTERNTIONIC LCD GROUP.

12.2 Scope

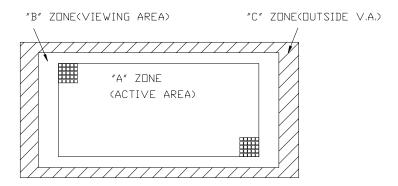
This document defines general provisions as well as inspection standards for LCD module supplied by EASTERNTIONIC LCD GROUP, except for those with special requirements from customer.

12.3 Definition

12.3.1 Definition of area

A Zone: Active area. B Zone: Viewing area

C Zone: Outside viewing area.



12.3.2 Definition of size

Large size(L): 1~6 pcs LCD screens are cut out of from each 14"×16" mother glass. Middle size(M): 7~50 pcs LCD screens are cut out of from each 14"×16" mother glass. Small size(S): more than 50 pcs LCD screens are cut out of from each 14"×16" mother glass.

12.4 Quality Specification

12.4.1 Conditions of Cosmetic Inspection

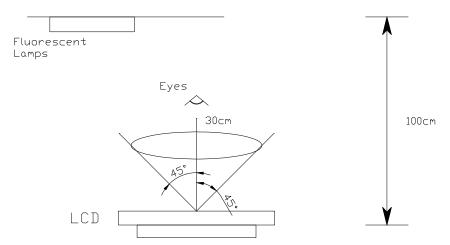
12.4.1 Test should be conducted under the following conditions:

Ambient temperature :22 \pm 5°C. Ambient humidity: 65 \pm 20%RH

Ambient Luminance: 40-watt fluorescent lamp.

An appearance test should be conducted by human sight at approximately 30 cm distance

from the LCD module under fluorescent light. Distance between LCD and fluorescent lamps should be 100 cm or more. Viewing direction for inspection is 45° from vertical against LCD.



12.4.1.2 When test the model of transmissive product must add the reflective plate.

12.4.2 Sampling plan

Unless otherwise agreed in writing, the sampling inspection shall be applied to the incoming inspection of customer.

- Lot size: Quantity of shipment lot per model
- Sampling type: Normal inspection, single sampling
- Sampling Level: Level II
- Sampling table: GB/T2828.1.1(GB-national standard of China)

12.4.3 Classification of defects and Acceptable quality level

Defects and classified as either a major or minor defect defined as bellows:

- Major defect: It is a defect that is likely to result in failure or to reduce materially the usability of the product for the intended function.
- Minor defect: It is a defect that will not result in functioning problem with deviation calssifiec.

The AQL for major and minor defects is defined as follows:

Partition	Definition	AQL
Major defect	Functional defective as product	0.4
Minor defect	Satisfy all functions as product but not satisfy cosmetic standard	1.0

12.4.4 Applicable instrument

- LCD module tester

- Multimeter
- Caliper
- Defect size filming standard

12.4.5 Inspection quality criterion

12.4.5.1 LCD panel part

The inspection specification as following list:

Classify	Item	Description of	Inspection	on criterion	Drawing
		defects			specification
Major	1.Non-display	Product no function	Not	accept	
defect	2.LCD with	Difference in Spec.	Not	accept	
	wrong view				
	direction`				
	3.Segment	Part or all pattern	Not	accept	
	missing	do not light up			
	4.Occur high	Current exceed	Not	accept	
	current	designed value			
	5. LC leakage	LC does not fulfill	Not	accept	
		the glass cell			
	6.Deviation	LCM Dimension	_	to dimensions	
	from drawing	difference from	noted in the	e specification	
		drawing and over	g and over		
		tolerance			
	7.Wrong type	Wrong polarizer	Not	accept	
	applied	attachment			
		Pin attached wrong	Not	accept	
		type applied			
	8.Incorrect	Pin attached wrong	Not	accept	
	pins quality	quantity applied			
Minor defect	9.Pattern	Segment fatter or	Dimension	Acceptable	
	deformation	smaller	(mm)	number	
			A≤0.1	Not count	
				(Should not be	
				connected to next dot)	→ _B ←
			0.10 <a≤0.15< td=""><td>1 pc / dot(only</td><td>1</td></a≤0.15<>	1 pc / dot(only	1
			0.10~/120.10	segment)or less	
				2 pcs / cell or less	
				(Should not be	
				connected to next	
				dot)	
				,	

			B ≤ 0.10	Not count	
Minor defect	10.Pinholes	Black spot/white spot at activated state	1m distance enlarge unde 2. Middle si Diameter(mm	n't be found at e and will not r electronic test ze LCD n) Accept QTY Not count 3 1 0 e LCD n) Accept QTY Not count 2 1 0 dot pattern: f the area of less than or half of one w one defect in ent arest diatance between two is 20mm Regarding the negative type STN and FSTN), riving voltage, the should be less or Φ ≤ 0.2). If the e is lower 0.3V I voltage, it should oltage , it can not ite dot base on ge.	$\Phi = (X+Y)/2$
	11.Blemishe s and foreign matters	Black spot/dust on LCD(non-display)	=		¥ Y

under electronic test:	$\Phi - (\mathbf{V} + \mathbf{V})/2$
	$\Phi = (X+Y)/2$
-Middle size LCD	
Diameter(mm) Accept QTY	
Φ≤ 0.15 Not count	
0.15<Φ≤ 0.25 3	
0.25<Φ≤ 0.35 1	
$\Phi > 0.35$ 0	
-Small size LCD	
Diameter(mm) Accept QTY	
$\Phi \le 0.15$ Not count	
0.15<Φ≤0.25 2	
$0.25 < \Phi \le 0.30$	
$\Phi > 0.30$ 0	
2.B zone	
1.5 times of acceptable	
largest diameter size of Zone	
A	
3.C zone	
Notcount.	
Negative panel:	
1. A zone	
-Large size LCD	
Diameter(mm) Accept QTY	
Φ ≤ 0.15 Not count	
0.15<Ф≤0.30 4	
0.30<Ф≤0.50	
$\Phi > 0.50$ 0	
-Middle&small size LCD	
Diameter(mm) Accept QTY	
$\Phi \le 0.15$ Not count	
$0.15 < \Phi \le 0.25$	
$\Phi > 0.25$ 0	
2. B zone	
1.5 times of acceptable	
largest diameter size of Zone	
A	
3.C zone	
No count	
The nearest diatance allowed	
between two black spot is	
20mm	

12.Black	Scratch on glass	Positive panel:	
lines and	or polarizer	1.A zone	1
scratches	surface.And	- Large size LCD	
scratches	foreign linear	Accept if can't find at 1m	
	matters in LCD	1	
	matters in LCD	distance and will not enlarge	
		under electronic test.	
		-Middle size LCD	
		Diameter(mm) Accept QTY	
		W≤ 0.02 Not count	
		$0.02 < W \le 0.03, L \le 4$ 2	
		$0.03 < W \le 0.05, L \le 3$ 2	
		$0.02 < W \le 0.03, L > 4 $ 0	
		$0.03 < W \le 0.05, L > 3 0$	
		W>0.05 As the spot criteria.	
		-Small size LCD	
		Diameter(mm) Accept QTY	
		W≤ 0.02 Not count	
		0.02< W≤ 0.03,L ≤4 2	
		$0.03 < W \le 0.05, L \le 2$	
		$0.02 < W \le 0.03, L > 4$ 0	
		$0.03 < W \le 0.05, L > 2 $ 0	
		W>0.05 As the spot criteria.	
		W > 0.05 The the spot efficient.	
		2.B zone	
		1.5 times of acceptable largest	
		diameter size of Zone A	
		3.C zone	
		Notcount.	
		Negative panel:	
		1. A zone	
		-Large size LCD	
		Diameter(mm) Accept QTY	
		$W \le 0.02$ Not count	
		$0.02 < W \le 0.03, L \le 5$ 3	
		$0.03 < W \le 0.05, L \le 4$ 2	
		$0.02 < W \le 0.03, L \ge 5$ 0	
		$0.02 < W \le 0.05, L > 3$ 0 $0.03 < W \le 0.05, L > 4$ 0	
		W>0.05 As the spot criteria.	
		v.o. 115 the spot effecta.	
		-Middle size LCD	

			Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03, L \le 4$ 2 $0.03 < W \le 0.05, L \le 2$ 2 $0.02 < W \le 0.03, L > 3$ 0 $0.03 < W \le 0.05, L > 2$ 0 $W > 0.05$ As the spot criteriaSmall size LCD Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03, L \le 3$ 2 $0.03 < W \le 0.05, L \le 3$ 1 $0.02 < W \le 0.03, L \le 3$ 2 $0.03 < W \le 0.05, L \ge 2$ 0 $0.03 < W \le 0.05, L \ge 2$ 0 $0.03 < W \le 0.05, L \ge 2$ 0 $0.03 < W \le 0.05, L \ge 2$ 0 $0.03 < W \le 0.05, L \ge 2$ 0 $0.03 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05, L \ge 2$ 0 $0.05 < W \le 0.05$	
Mintor defect	13. Scratch on PI coating	PI coating scratched	The visible scratch of A zone can not be accepted at 30cm view distance.	
Mintor defect	14. Rainbow	Arches, circular or parallel colorful spread	According to the limit specimen	
Mintor defect	15. Bubbles or wrinkles in polarizer	Bubbles or wrinkles between polarizer and glass	A zone:The visible defect can not be accepted at 30cm view distance. B zone: Not count	
Mintor defect	16. Position of polarzer attachment	Wrong polarizer attachment in position or dimension	Polarizer protruding from edge of glass and exceeding/within the maximum external dimension of LCD	

Mintor	17. Ink	17.1 Ink	Not acce	pt			
defect	printing	line/pattern					
	defect	broken		6.1 .1.1	.1.		
		17.2 Ink pattern/line	_	f the thick n equal to		-	
		jagged		r accordii			
		J.,88	specimen		6		
		17.3 Light			with	current	
		leakage		ht appears			
			_	le or scra misalignr			
				nhole spec		_	
		17.4 Ink printing	Reject if than 1/2	the thick	or thin	in more	
		pattern/line uneven		w. hen W1-V	V2<1/3V	V	
							W1 W2
Mintor	18. Pin defect	18.1 Corrosion	Pin	incomin	~	defect:	
defect	18. Fill defect	or foreign		incomin damage(i	_		
		material on		damaged)			
		terminal legs		om glass	s or t	erminal	
		10 A D'	legs.Not		· C·	··	
		18.2 Pin deviation over	Accordin	ng to the s	pecifica	шоп	
		tolerance					
Mintor	19. Chipped	19.1 Chip in	a	b	c	accept	
defect	glass on	lead contact				QTY	
	comer	area.	a≤5mm L>5m	b≤W	c≤T	3	
			m			3	ITO
			a <l< td=""><td>b≤W</td><td>c≤T</td><td>3</td><td></td></l<>	b≤W	c≤T	3	
							T
			L<5m				b o o
			m				
		19.2 Others	Not exc	ceed 1/2			AT.
			width of	seal	c≤T	3	
							100

Mintor defect	20. Glass	chip on edge	a	b	С	accept QTY	\$ 0
			a≤5mm	Not exceed 1/2 width of seal	c≤T	3	C
Mintor defect	21. Clipped electrode pad	21.1Glass chip on ITO edge 21.2 Glass chip	a a≤4mm (and not exceed 4 ITO termina 1 a	b b≤W/4 b	c c≤T	accept QTY 3	ITD V
		on ITO back	a≤5mm	b≤W/3	c≤T	QTY 3	
Mintor defect	22. Mechanical	Extended crack inspector shall	b		accept	QTY	
	damage	attempt to remove the chip with tweezers,re-eval uate if the remaining defect is still a crack or a chip	b≤W/4		2		
Mintor defect	23.Gla	Not acce	pt				

Remark:

The minimum space between any 2 defects(spot,dirt) should more than 20mm, and max. allowed defect QTY in total:

Large size LCD: Zone A≤ 5/unit, Zone B≤ 5/unit; Middle size LCD: Zone $A \le 3/unit$, Zone $B \le 3/unit$; Small size LCD: Zone A≤ 2/unit, Zone B≤ 2/unit;

12.4.5.2 Other part

The inspection specification as following list:

NO.	Items	Criterion of defects	AQL
1	Backlight	 Lumination source flickers. Using spot, lines and contamination standard of LCD to 	Major Minor
		judge the spots or scratches defect on backlight.	
		3. Not allow unlighted on backlight.	Major
		4. Colour and luminance of backlight should correspond its	Major
	DGD G0D	specification.	3.61
2	PCB,COB	1.COB seal may not have pinholes larger than 0.2mm or contamination.	Minor
		2.COB seal surface may not have pinholes through to the IC.	Minor
		3. The height of COB should not exceed the height indicated in the assembly diagram.	Major
		4. Beyond 2mm of the seal area, there may not have sealant on the PCB.	Minor
		5.No oxidation or contamination on PCB connector.	Minor
		6.Parts on PCB should correspond the characteristic, and not	Major
		allow wrong parts, missing parts or additional parts.	
		7. The jumper on the PCB should correspond to the characteristic.	Minor
		8.The solder which gets on bezel,LED pad,zebra pad or	Major
		screw hole pad should be smoothed down.	3
		1. No unmelted solder pastes on the PCB.	Minor
3	Soldering	2. No cold solder joints, solder connection missing, oxidation of solder.	Minor
		3. No short circuits in components on PCB.	Minor
4	General Appearance	1. No oxidation, contamination, curves, cracks or bends on interface Pin of TCP.	Minor
		2. No solder residue or solder balls on product.	Minor
		3. The IC on TCP may not be damaged.	Major
		4. The residual rosin or tin oil of soldering(component or chip component) is not turned into brown or black colour.	Minor
		5. Packing method correspond the specification.	Major
		6. Dimension and structure correspond the specification sheet.	Major
		7. No dirt and break on the heat seal.	Major

12.5 Reliability

The LCD module shall not fail the following reliability test.

Item	Condition			Criterion
High temperature	$+70^{\circ}\text{C} \pm 2^{\circ}\text{C}$, 8 hours			
operation				
Low temperature	$-20^{\circ}\text{C} \pm 2^{\circ}\text{C}$, 8 ho	ırs		1.Total current
operation				consumption
Humidity	Operation	40 °C ± 2 °C ,93% ±	2%RH,8	should be below
		hours		double of initial
	Storage	40 °C ± 2 °C ,93% :	± 2%RH,	value.
		24 hours		2.Cosmetic defects
High temperature	+80°C ±2°C, 10 h	ours		should not be
storage				happened
Low temperature	$-30^{\circ}\text{C} \pm 2^{\circ}\text{C}$, 10 h	ours		
storage				
Thermal shock	-20°C ~ +70°C			
storage	60min~60min, 5 cy	cles		
Vibration test	Amplitude:0.7~1.0	mm,frequency:50Hz	,30min	
	in each direction(X	,Y,Z)		
Shock test	To be measured aft	er dropping from 60d	cm or	
	80cm high on the c	oncrete surface in pa	cking	
	state.(weight≥15K	g,dropping height 60	Ocm;	
	Weight<15Kg,dro	pping height 80cm)		
		Dropping n	nothod	
		corner drop		
		A corner	: once	
	G B	Edge dropp	· ·	
		A B,C,D ed		
	60/8	Ocm Face dropp E,F,G fa	•	
		oncrete Surface		
	///////////////////////////////////////	////		

Remark: The function test shall be conducted after 4 hours storage at the normal temperature and humidity after removed from the test chamber.

13. Precaution For Using LCM

1. LIQUID CRYSTAL DISPLAY (LCD)

- LCD is made up of glass, organic sealant, organic fluid, and polymer based polarizers. The precautions should be taken when handing,
- (1). Keep the temperature within range of use and storage. Excessive temperature and humidity could cause polarization degredation, polarizer peel off or bubble.
- (2). Do not contact the exposed polarizers with anything harder than an HB pencil lead. To clean dust off the display surface. Wipe gently with cotton. Chamois or other soft material soaked in petroleum benzin.
- Wipe off saliva or water drops immediately. Contact with water over a long period of time may cause polarizer deformation or color fading, while an active LCD with water condensation on its surface will cause corrosion of ITO electrodes.
- (4). Glass can be easily chipped or cracked from rough handing. especially at corners and edges.
- (5). Do not drive LCD with DC voltage.

2. Liquid Crystal Display Modules

2.1 Mechanical Considerations

LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted.

- (1). Do not tamper in any way with the tabs on the tabs on the metal frame.
- (2). Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattem.
- (3). Do not touch the elastomer connector, especially insert an backlight panel (for example, EL).
- (4). When mounting a LCM make sure that the PCB is not under any tress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.
- (5). Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing piels.

2.2. Static Electricity

LCM contains CMOS LSI's and the same precaution for such devices should apply, namely

(1). The operator should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.

- (2). The modules should be kept in antistatic bags or other containers resistant to static for storage.
- (3). Only properly grounded soldering irons should be used.
- (4). If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.
- (5). The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.
- (6). Since dry air is inductive to statics, a relative humidity of 50-60% is recommended.
- 2.3. Soldering
- (1). Solder only to the I/O terminals.
- (2). Use only soldering irons with proper grounding and no leakage.
- (3). Soldering temperature: 280 $^{\circ}\text{C} \pm 10^{\circ}\text{C}$
- (4). Soldering time: 3 to 4 sec.
- (5). Use eutectic solder with resin flux fill.
- (6). If flux is used, the LCD surface should be covered to avoid flux spatters. Flux residue should be removed after wards.

2.4. Operation

- (1). The viewing angle can be adjusted by varying the LCD driving voltage V0.
- (2). Driving voltage should be kept within specified range; excess voltage shortens display life.
- Response time increases with decrease in temperature.
- Display may turn black or dark blue at temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".
- (5). Mechanical disturbance during operation (such as pressing on the viewing area) nay cause the segments to appear "fractured".

2.5. Storage

If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. Never swallow the fluid. The toxicity is extremely low but caution should be exercised at all the time.

2.6. Limited Warranty

Unless otherwise agreed between EASTERNTRONIC and customer, EASTERNTRONIC will replace or repair any of its LCD and LC, which is found to be defective electrically and visually when inspected in accordance with EASTERNTRONIC acceptance standards, for a period on one year fron data of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of EASTERNTRONIC is limited to repair and/or replacement on the terms set forth above. EASTERNTRONIC will not responsible for any subsequent or consequential events.

14. Declaration of conformity regarding the limitation of dangerous substances

深圳易事通液晶显示模块有限公司

SHENZHEN EASTERNTRONIC LCM CO., LTD.

4F, B3 Building, FuYuan Industrial Zone, FuYong Town,

BaoAn District, ShenZhen, P.R.China

DECLARATION OF CONFORMITY REGARDING THE LIMITATION OF DANGEROUS SUBSTANCES

WE, SHENZHEN EASTERNTRONIC LCM CO., LTD,

Declare that the product of CS2004C-D-YSXFDYN-104 complies with: The directive 2002/95/EC Dated 2003/01/27 regarding the limitation of dangerous substances, in particular to clause 4 which forbids the use of the following elements:

- Lead
- Mercury
- Cadmium
- Hexavalant chromium
- Polybrominated biphenyls
- Polybrominated diphenylethers

And to the annex which points out the exempted implementations \square To the directive 73/23/eec dated 1973/02/19 and the standard EN60335-1 regarding prohibition of following elements:

- 0ils containing polychlorinated biphenyl
- Asbestos
- Radioactive substances

Name: Ding

SHENZHEN EASTERNTRONIC LCM CO., LTD.

Issued on Feb 26, 2009

According with the proposal of Technical Adaption Committee (TAC) of a limit of 0.1% by weight for lead hexavalent chromium, mercury, PBBs and PBDRs and 0.01% by weight for Cadmium.